PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4080743

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MING-YEN CHIU	09/21/2016
HSIN-CHIEH HUANG	09/22/2016
CHING-FU CHANG	09/22/2016

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15284425

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	252011-6120
NAME OF SUBMITTER:	DANIEL R. MCCLURE
SIGNATURE:	/Daniel R. McClure/
DATE SIGNED:	10/03/2016

Total Attachments: 2
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ASSIGNMENT

WHEREAS, Ming-Yen CHIU, Hsin-Chieh HUANG, and Ching-Fu CHANG hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **PACKAGE STRUCTURE WITH BUMP**
Filed: ____________ Serial No. ____________
Executed on: ____________

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2016, 09, 21 Ming-Yen Chiu
Date Name: Ming-Yen CHIU (Last name: CHIU)

2016. 9. 22 Huang, Hsin-Chieh
Date Name: Hsin-Chieh HUANG (Last name: HUANG)

2016. 9. 22 Ching-Fu CHANG
Date Name: Ching-Fu CHANG (Last name: CHANG)